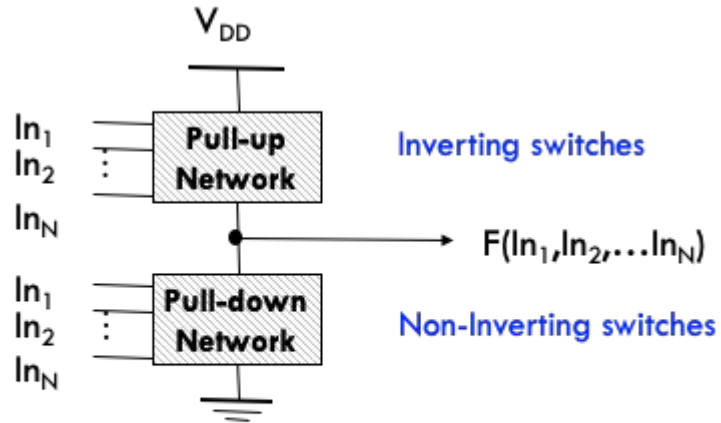


Discussion 10

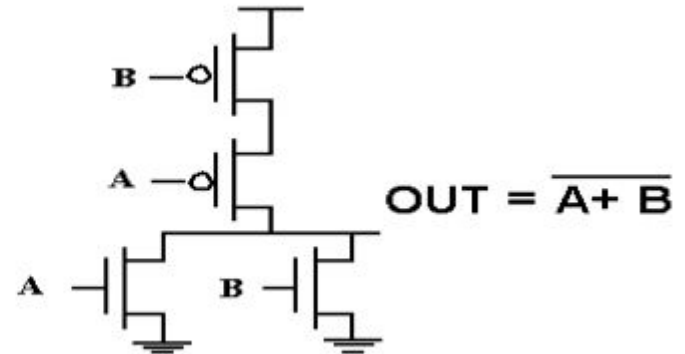
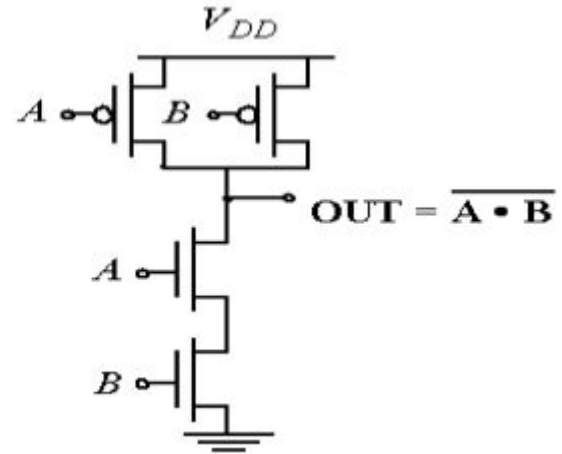
Gate Sizing, RC Delay, Logical Effort, Power/Energy,
Adders

CMOS Logic

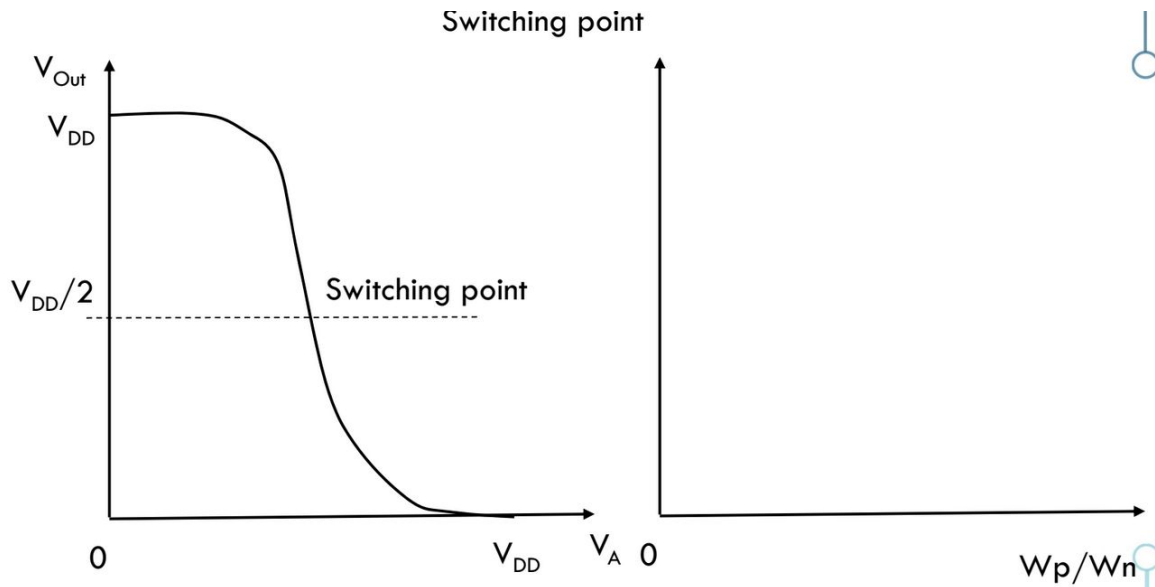
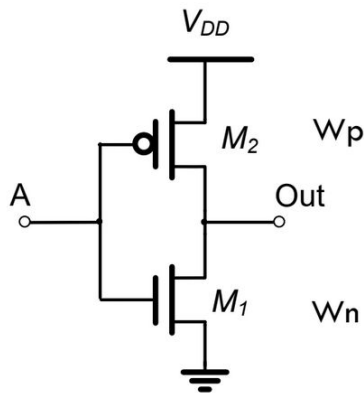


PUN and PDN are **dual** logic networks

PUN and PDN functions are **complementary**



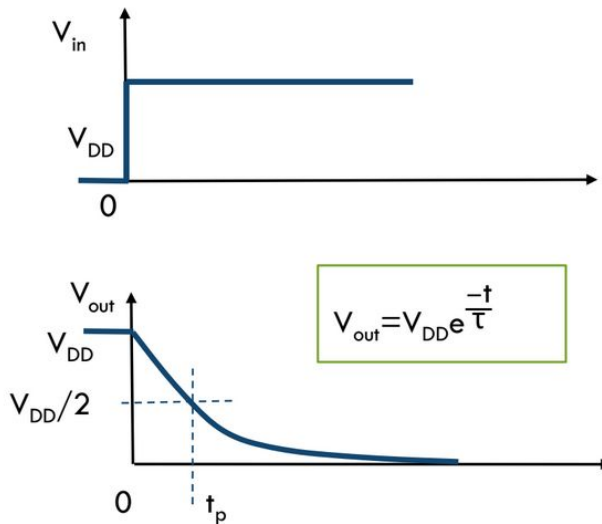
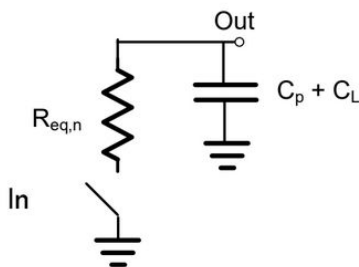
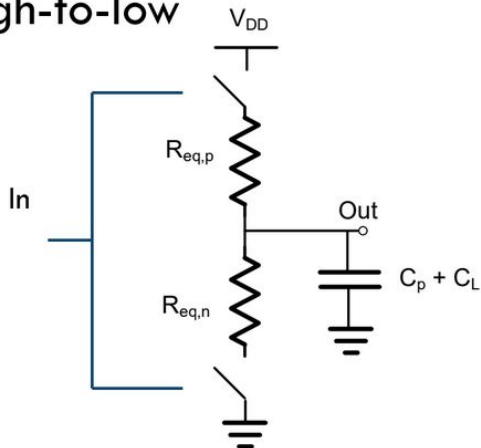
Inverter Sizing



- R_{on} of each FET is inversely proportional to its width
- Assume $V_{th,n} = V_{th,p}$
- Assume $R_{on,n} = R_{on,p}$ for the same width unless otherwise specified
- $W_p = W_n$ = switching threshold of $V_{DD}/2$
- If $W_p \gg W_n$, V_m approaches V_{DD} | If $W_n \gg W_p$, V_m approaches 0 (exponentially)

Inverter RC Delay (High -> Low)

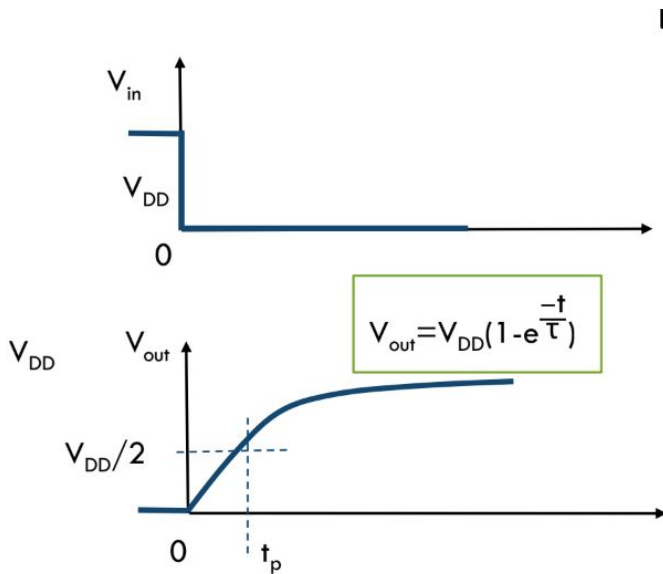
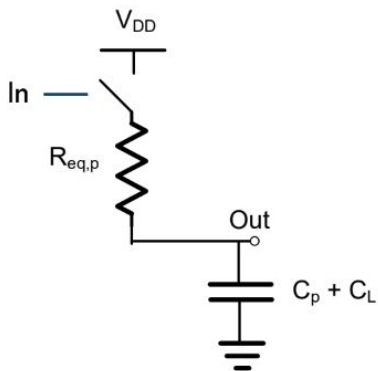
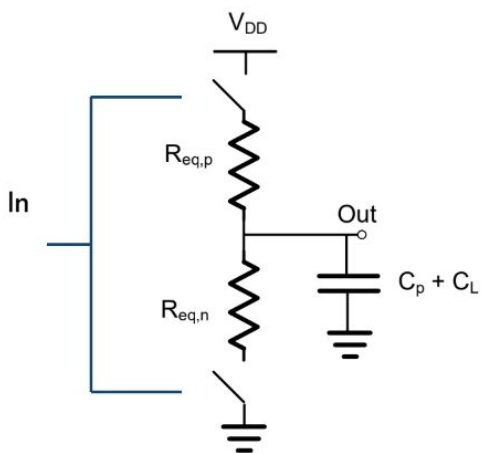
High-to-low



$$t_{p,HL} = (\ln 2)\tau = 0.7 R_{eq,n}(C_p + C_L)$$

- High to low output transition time governed by strength of NMOS pulling low
- Can lower the time constant by increasing the NMOS width

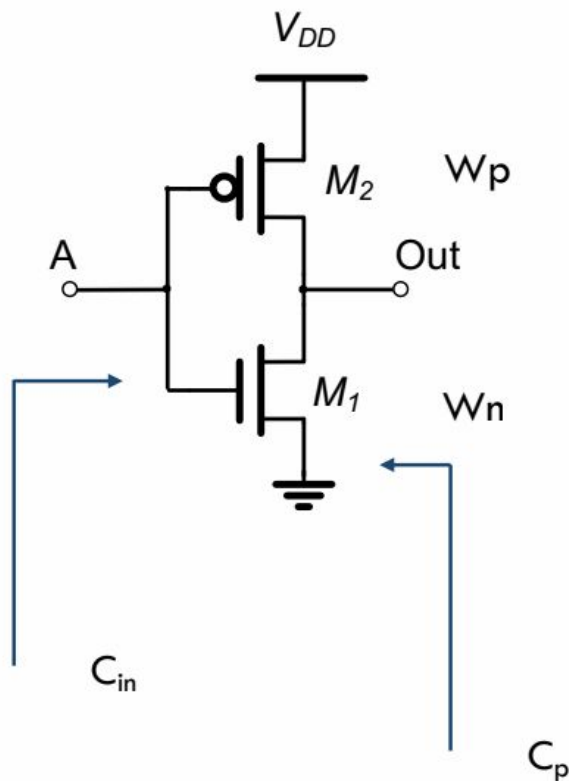
Inverter RC Delay (Low -> High)



$$t_{p,LH} = (\ln 2)\tau = 0.7 R_{eq,p}(C_p + C_L)$$

- Low to high output transition time governed by strength of PMOS pulling high
- Can lower the time constant by increasing the PMOS width

Inverter Sizing

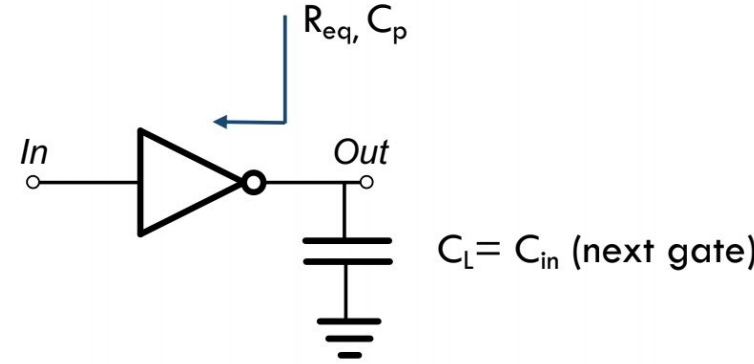


- C_{in} (gate input capacitance) and C_p (intrinsic drain capacitance) are proportional to W
 - You may see C_p referred to C_d in other sources
 - $C_p = \gamma C_{in}$
- How does the inverter delay change if either PMOS/NMOS width is doubled?
- If both widths are doubled, does the intrinsic (unloaded) delay improve?
- Inverters are usually sized to equalize high->low and low->high delays

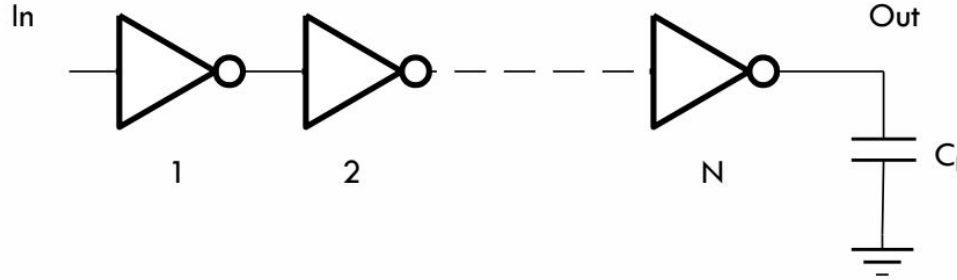
Inverter Delay

$$\begin{aligned}t_{\{p,inv\}} &= R_{\{eq\}} (C_{\{p,tot\}} + C_L) \\&= R_{\{eq\}} C_{\{p,tot\}} (1 + (C_L / C_{\{p,tot\}})) \\&= R_{\{eq\}} C_{\{p,tot\}} (1 + (C_L / C_{\{in\}} \gamma)) \\&= R_{\{eq\}} C_{\{p,tot\}} (1 + (f / \gamma)) \\&= \tau_{\{inv\}} (1 + (f / \gamma))\end{aligned}$$

- Delay can be split into 2 parts, intrinsic and extrinsic
- Fanout f = ratio between output and input cap (C_L / C_{in})
- This delay formula can be generalized for any CMOS gate
 - $t_{\{p,gate\}} = \tau_{\{inv\}} (p + gf/\gamma)$
 - Often assume $\gamma = 1$



Sizing an Inverter Chain



- We want to minimize the delay of this inverter chain
- Assume the 1st inverter has a size of 1

$$\text{Delay} = t_{p1} + \dots + t_{pn} = (1+f_1) + (1+f_2) + \dots + (1+f_n)$$

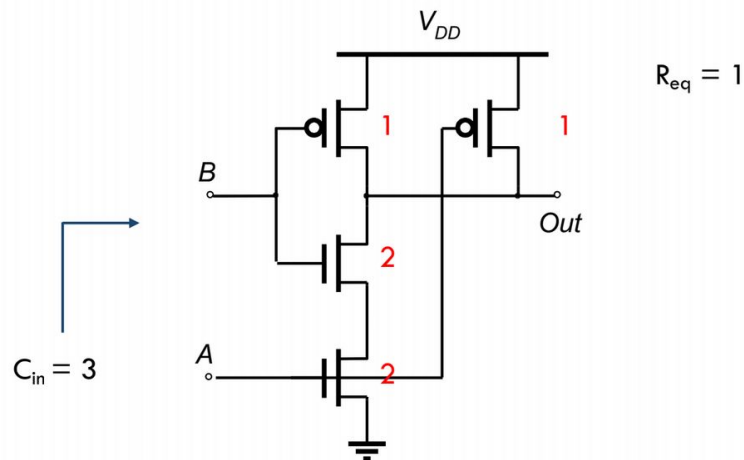
Take partial derivatives of this expression wrt C_2, \dots, C_n

Solution is $f_1 = f_2 = f_3 = \dots = f_N$

Each inverter has a fanout = the n -th root of F (total fanout)

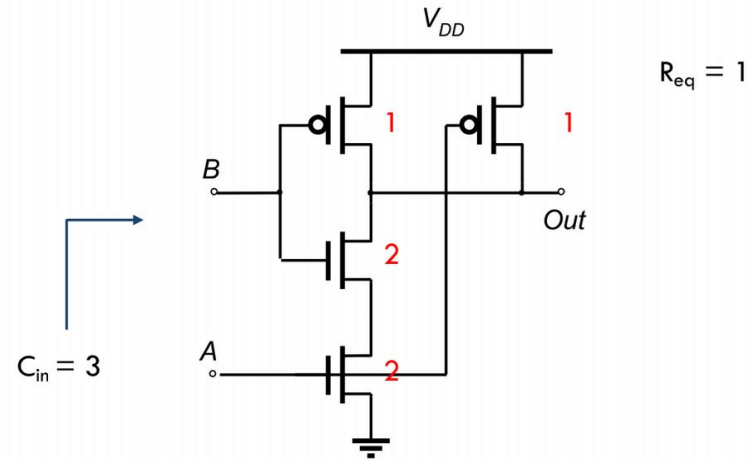
Logical Effort

- g = logical effort
- To find g for a CMOS gate:
 1. Size the gate to have R_{eq} equal to that of an inverter
 2. Find the input capacitance of the gate (for a particular input)
 3. Take the ratio $C_{in,gate} / C_{in,inv}$
- For a NAND2 gate: $g = 3/2$
- For a NOR2 gate: $g = 3/2$
- How do these change if the PMOS is half as strong as an nMOS?
- Can the logical effort be different for different inputs?



Intrinsic Delay

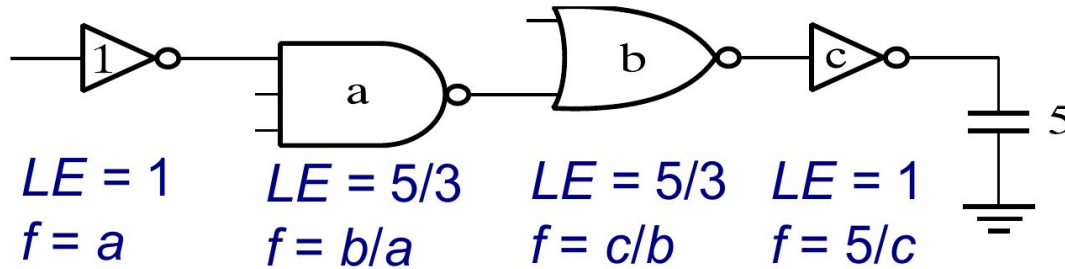
- p = intrinsic delay
- To find p for a CMOS gate:
 1. Size the gate to have R_{eq} equal to that of an inverter
 2. Find the output (intrinsic) capacitance of the gate
 3. Take the ratio $C_{out,gate} / C_{out,inv}$
- For a NAND2 gate: $g = 4/2$
- For a NOR2 gate: $g = 4/2$
- How do these change if the PMOS is half as strong as an nMOS?



Path Delay

- Path logical effort $G = g_1 * g_2 * \dots * g_N$
- Path fanout $F = C_L / C_{\{in,1\}}$
 - This is called H in lecture
- Branching factor $b_i = \text{ratio of total cap seen / on-path cap}$
- Path total effort $H = GFB$
 - This is called F in lecture
- We want to minimize the delay of a path through a series of gates
 - Each stage i in the chain has an effective fanout $g_i * f_i$
 - The solution is to make the effective fanout of each stage the same
 - $EF_{\{opt\}} = H^{\{1/N\}}$
 - $EF = g_i * f_i = g_i * (C_{\{load\}} / C_{\{in\}})$
 - $C_{\{in\}}$ (i.e. the gate size) $= g_i * C_{\{load\}} / EF$
- The optimal path delay $D = N * H^{\{1/N\}} + p_1 + \dots + p_N$

Sizing a Logic Path for Minimum Delay



- This example assumes the NMOS is twice as strong as the PMOS
- EF/stage is calculated as the 4th-root of $G \cdot F$
- $g_i \cdot f_i = \text{EF of stage } i$
- Easier to calculate gate sizes from the load cap backwards

Electrical fanout, $F = 5$

$$\Pi LE = 25/9$$

$$PE = 125/9$$

$$EF/\text{stage} = 1.93$$

$$a = 1.93$$

$$b = 2.23$$

$$c = 2.59$$

From the back

$$5/c = 1.93$$

$$(5/3)c/b = 1.93$$

$$(5/3)b/a = 1.93$$

Sizing a Logic Path for Minimum Delay (Branching)

Select gate sizes y and z to minimize delay from A to B

Logical Effort:

$$LE = (4/3)^3$$

Electrical Fanout:

$$F = C_{out}/C_{in} = 9$$

Branching Effort:

$$B = 2 \cdot 3 = 6$$

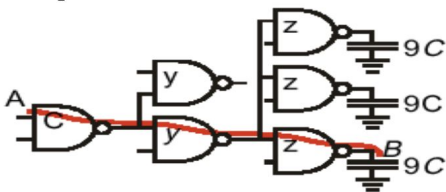
Path Effort:

$$PE = LE \cdot F \cdot B = 128$$

Best Effective Fanout: $EF = PE^{1/3} \approx 5$

Delay:

$$D = 3 \cdot 5 + 3 \cdot 2 = 21$$



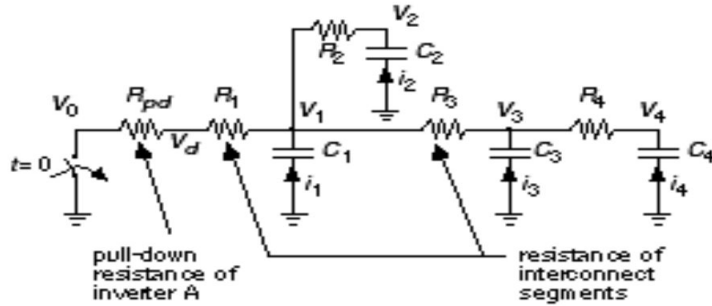
Work backward for sizes:

$$z = \frac{9C \cdot (4/3)}{5} = 2.4C$$

$$y = \frac{3z \cdot (4/3)}{5} = 1.9C$$

- This example also assumes the NMOS is twice as strong as the PMOS
- Note that when calculating the size y , you must consider the total load cap ($3z$) instead of just z
- Recall: $D_{opt} = N * H^{1/N} + p_1 + \dots + p_N$

Elmore Delay Approximation



- Approximates the dominant time constant of a RC network for a given input and output node
- 2 methods (same result):
 1. Take every capacitor and multiply it by the sum of resistors on the path charging it
 2. Take every resistor on the path and multiply it by the sum of capacitances it charges

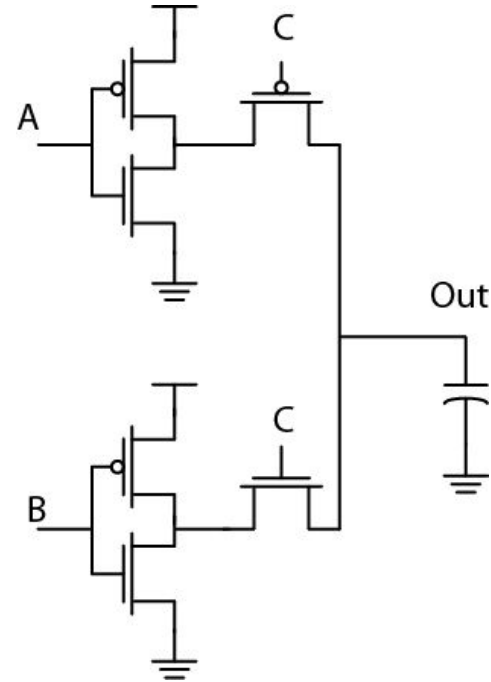
$$\tau_{D4} = \sum_{k=0}^4 C_k R_{4k} = C_0 R_{pd} + C_1 (R_{pd} + R_1) + C_2 (R_{pd} + R_1) + C_3 (R_{pd} + R_1 + R_3) + C_4 (R_{pd} + R_1 + R_3 + R_4) = R_{pd} (C_0 + C_1 + C_2 + C_3 + C_4) + R_1 (C_1 + C_2 + C_3 + C_4) + R_3 (C_3 + C_4) + R_4 C_4$$

Energy and Power

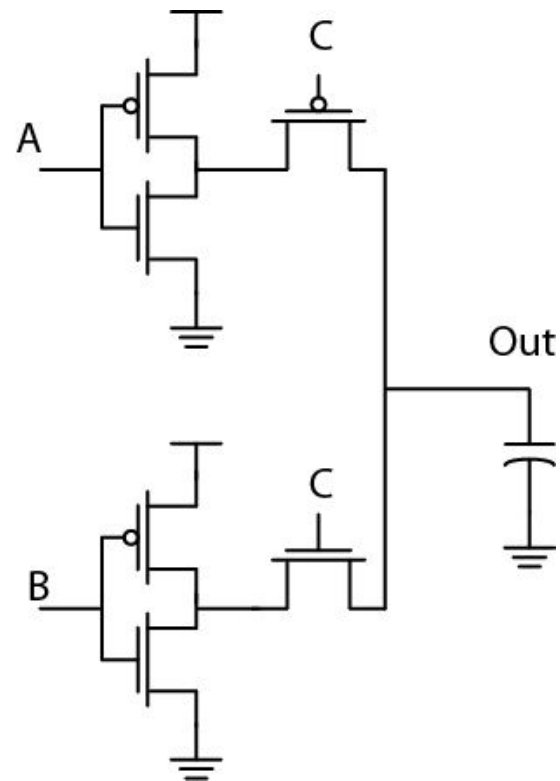
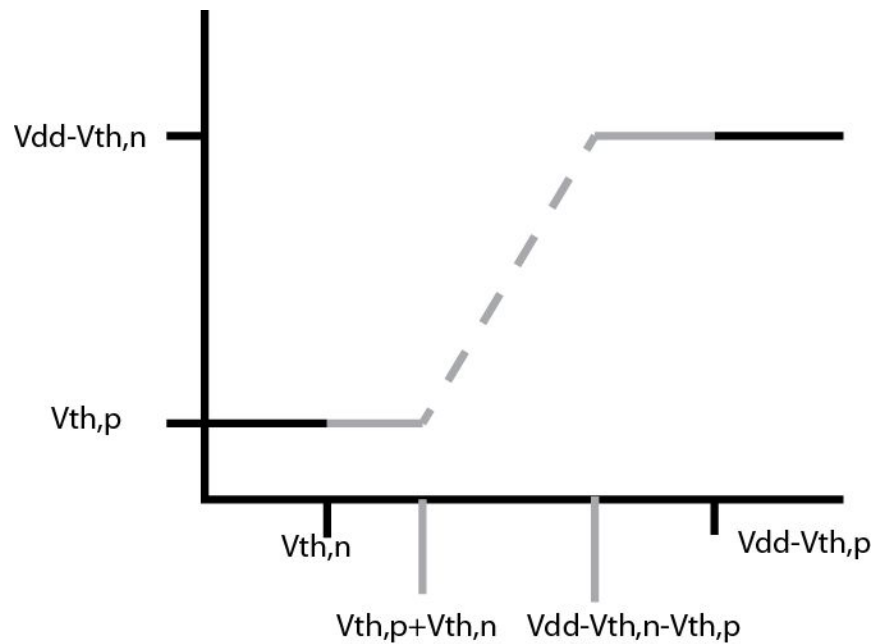
- CV^2 joules drawn from supply when charging cap to VDD
- $\frac{1}{2} CV^2$ stored on capacitor
- No additional charge drawn from supply when the cap discharges
- The other $\frac{1}{2} CV^2$ is burned on the charging resistance and dissipates as heat
- Dynamic switching power = $f C V^2 \alpha_{\{0 \rightarrow 1\}}$

Problem

- Assume $A = V_{DD}$, $B = 0V$
- $V_{thn} = 0.2V$
- $|V_{thp}| = 0.3V$
- $R_p = R_n$
- Draw a VTC when V_c is swept from 0 to V_{DD}

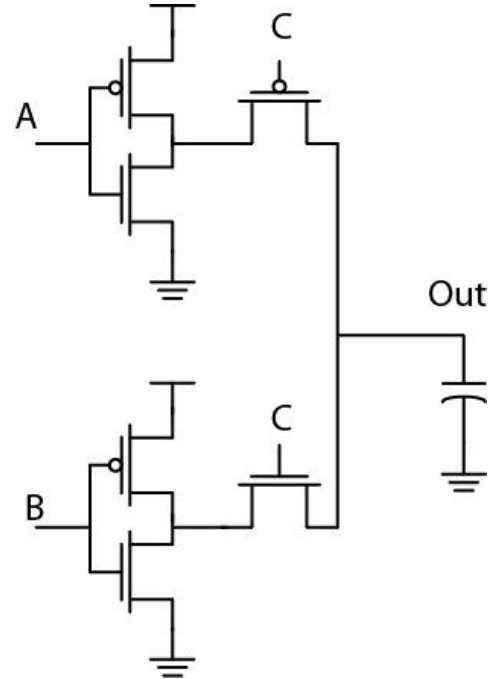


Problem



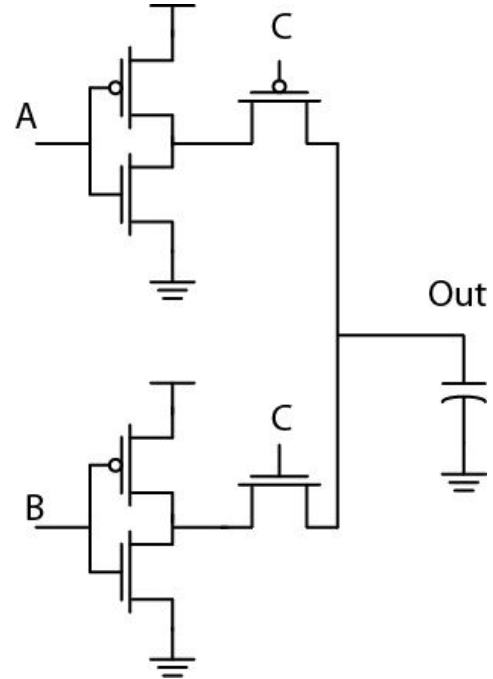
Problem

- What is the energy pulled from the supply when $B = 1$, $C = 0$, and A goes from 1 to 0? Assume C_L is initially at 0V.
 - The output cap is charged from 0V to V_{DD}
 - $C * V_{DD}^2$
- Using the final voltage from the last part as the new initial condition, how much energy is dissipated when C goes from 0 to 1?
 - $\frac{1}{2} C * V_{DD}^2$



Problem

- What is the energy pulled from the supply when $A = 1$, $C = 1$, and B goes from 1 to 0? Assume C_L is initially 0V.
 - Recall $E_{VDD} = C_L * VDD * V_{\Delta}$, where V_{Δ} is the change in voltage across the capacitor
 - $C_L * VDD * (VDD - V_{thn})$
- Using the final voltage from the last part, how much energy is dissipated when C goes from 1 to 0?
 - $\frac{1}{2} C_L ((VDD - V_{thn})^2 - (V_{thp})^2)$
 - Cap starts at $VDD - V_{thn}$ and ends at V_{thp} . The energy difference is dissipated.



Adders

- Let's look at last semester's discussion slides:

<http://inst.eecs.berkeley.edu/~eecs151/sp19/files/discussion11.pdf>